CLAIM AMENDMENTS

Claims 1-36 (Canceled).

37. (Previously Presented) A device comprising:

a first and second bond pad, said first and second bond pads comprising a nickel coated metal;

a first gold coating on said first and second bond pad, the first gold coating having a given thickness;

a second gold coating on said second bond pad, said second gold coating and said first gold coating forming a composite gold coating having another thickness greater than the thickness of said first gold coating;

a support structure having parallel surfaces, said second bond pad on one parallel surface of said support structure; and

a chip on another parallel surface of said support structure, said chip and said second bond pad linked by an electrically conductive element.

38. (Previously Presented) The device of claim 37 wherein the first bond pad comprises a nickel coated copper.

39. (Previously Presented) The device of claim 38 wherein the second bond pad comprises a nickel coated aluminum.

Claims 40 and 41 (Canceled).

42. (Previously Presented) The device of claim 37 wherein the composite gold coating on the second bond pad has a thickness of about 0.5 microns.

43. (Currently Amended) The device of claim 37 wherein the first and second bond pads coexist on ~~a planar support structure~~ said one parallel surface of said support structure.

Claims 44-49 (Canceled).

50. (Previously Presented) A package integrated circuit device comprising:

a support structure having parallel surfaces;

a die on one of said parallel surfaces;

a plurality of bond pads on another of said parallel surfaces, at least one of said plurality of bond pads coupled to said die by a wire; and

a first and second gold coating of different thickness, said first gold coating on said bond pad coupled to said die by the wire, said second gold coating on the bond pads not coupled to said die by a wire.

51. (Previously Presented) The device of claim 50 including surface mount material on said bond pads not coupled to said die by a wire.

52. (Previously Presented) The device of claim 50 wherein the first gold coating is thicker than said second gold coating.

53. (Previously Presented) The device of claim 52 wherein the first gold coating has a thickness of about 0.5 microns.

54. (Previously Presented) The device of claim 52 wherein the second gold coating has a thickness of approximately 0.1 to 0.3 microns.

55. (Previously Presented) The device of claim 50 wherein the thickness of the second gold coating is sufficiently low to reduce the likelihood of solder ball joint embrittlement.

56. (Previously Presented) The device of claim 50 wherein the support structure is a laminate structure.

57. (Previously Presented) The device of claim 50 wherein the support structure has an opening and said bond pad coupled to said die by said wire is coupled to said die through the opening in said structure.

58. (Previously Presented) The device of claim 50 wherein said plurality of bond pads comprise a nickel coated metal.

59. (Previously Presented) The device of claim 58 wherein said bond pad coupled to said die by said wire comprises a nickel coated metal that is different from the nickel coated metal of the bond pads not coupled to said die by said wire.

60. (Previously Presented) The device of claim 59 wherein one nickel coated metal is aluminum and the other nickel coated metal is copper.

61. (Previously Presented) The device of claim 37 wherein the first gold coating has a thickness of approximately 0.1 to 0.3 microns.

62. (Previously Presented) The device of claim 37 wherein the electrically conductive element is a gold wire.

63. (Previously Presented) The device of claim 62 wherein the support structure has an opening and said wire passes through said opening.